

| L Number | Hits | Search Text   | DB  | Time stamp       |
|----------|------|---|---|------------------|
| 1        | 0    | (hysol near "4451") with ultraviolet  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2003/09/05 14:11 |
| 2        | 41   | hysol near "4451"   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2003/09/05 14:12 |
| 3        | 0    | (hysol near "4451") with light  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2003/09/05 14:12 |
| 4        | 0    | (hysol near "4451") with photo  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2003/09/05 14:12 |
| 5        | 6    | (hysol near "4451") same (light photo ultraviolet)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2003/09/05 14:14 |
| 6        | 22   | hysol with (light photo ultraviolet)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2003/09/05 14:21 |
| 7        | 55   | "3140" with (light photo ultraviolet)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2003/09/05 14:22 |
| 8        | 2    | "3140" with dow with (light photo ultraviolet)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2003/09/05 14:22 |
| -        | 162  | ((micromachine microelectronic) and ((lid cap) with (spacer bead)))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 07:09 |
| -        | 149  | ((micromachine microelectronic) and ((lid cap) with (spacer bead))) and substrate   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/27 08:01 |
| -        | 9    | ((micromachine microelectronic) and ((lid cap) with (spacer bead))) and substrate) and ((bond bonding) adj pad)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/26 09:27 |
| -        | 140  | ((micromachine microelectronic) and ((lid cap) with (spacer bead))) and substrate) not (((micromachine microelectronic) and ((lid cap) with (spacer bead))) and substrate) and ((bond bonding) adj pad))              | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/26 10:11 |
| -        | 7    | ((micromachine microelectronic) and ((lid cap) with (spacer bead))) and substrate) not (((micromachine microelectronic) and ((lid cap) with (spacer bead))) and substrate) and ((bond bonding) adj pad))) and package | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/26 10:25 |
| -        | 0    | 5397897.pn. and micromachine  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/26 10:26 |
| -        | 0    | 5397897.pn. and microelectronic   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/26 10:27 |
| -        | 3    | ((micromachine microelectronic) and ((lid cap) with dam)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/26 10:47 |
| -        | 116  | 257/619   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/26 13:58 |

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| - | 516   | 257/620   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/26 13:58 |
| - | 410   | 257/621   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/26 13:58 |
| - | 1006  | 257/619 257/620 257/621   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/26 13:59 |
| - | 89    | (257/619 257/620 257/621) and (lid cap cover) and ((bond bonding)adj pad)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/26 14:03 |
| - | 396   | ((micromachine micromachined microelectronic) near1 (device package)) and (lid cap) and substrate   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/27 08:04 |
| - | 41    | ((micromachine micromachined) near1 (device package)) and (lid cap) and substrate   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/27 08:04 |
| - | 10941 | silicon near2 ceramic   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/27 14:06 |
| - | 2701  | (silicon near2 ceramic) and (cap lid cover)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/27 14:07 |
| - | 134   | silicon near2 ceramic) with(cap lid cover   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/27 14:07 |
| - | 53    | ((silicon near2 ceramic) with(cap lid cover)) and (semiconductor micromachined micromachine)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2001/11/27 14:08 |
| - | 51909 | (micromachine micromechanical micromirror microelectronic)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 07:10 |
| - | 54209 | (micromachine micromachined micromechanical micromirror microelectronic)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:18 |
| - | 165   | ((micromachine micromachined micromechanical micromirror microelectronic) ) and ((block blocking) near (adhesive material))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 07:19 |
| - | 2     | "6274927"   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 08:10 |
| - | 8     | "5962810"   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 07:19 |
| - | 9     | "6274927" "5962810"   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 07:19 |
| - | 5     | 5962810.URPN.   | USPAT                                       | 2002/03/25 07:23 |
| - | 19    | ("4530152"   "4649418"   "4691225"   "4801998"   "4814943"   "4890383"   "5043004"   "5068713"   "5102829"   "5126818"   "5192681"   "5241133"   "5250470"   "5336931"   "5428188"   "5436203"   "5474957"   "5578525"   "5593926").PN. | USPAT                                       | 2002/03/25 07:24 |

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| - | 23   | ("4530152"   "4649418"   "4691225"  <br>"4801998"   "4890383"   "5043004"  <br>"5102829"   "5126818"   "5192681"  <br>"5241133"   "5250470"   "5336931"  <br>"5436203"   "5474957"   "5530278"  <br>"5578525"   "5593926"   "5612513"  <br>"5776798"   "5861680"   "5866953"  <br>"5893723"   "5918113").PN.  | USPAT                                       | 2002/03/25 07:26                     |
| - | 0    | 6274927.URPN.   | USPAT                                       | 2002/03/25 07:29                     |
| - | 38   | ("3838984"   "4691225"   "4801998"  <br>"5057905"   "5070041"   "5117279"  <br>"5122862"   "5159432"   "5230759"  <br>"5256901"   "5258094"   "5336931"  <br>"5435057"   "5436203"   "5497032"  <br>"5529959"   "5644169"   "5656857"  <br>"5776798"   "5859471"   "5861680"  <br>"5866953"   "5867368"   "5877043"  <br>"5877546"   "5893723"   "5895222"  <br>"5905301"   "5949655"   "5950074"  <br>"5962810"   "5972738"   "5981314"  <br>"5989941"   "5998862"   "6034429"  <br>"6092281"   "6117705").PN. | USPAT<br>USPAT                              | 2002/03/25 07:29<br>2002/03/25 07:29 |
| - | 7683 | ((micromachine micromachined<br>micromechanical (micromirror adj device))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 08:00                     |
| - | 1427 | ((micromachine micromachined<br>micromechanical (micromirror adj device))<br>) and substrate and (wire wiring)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 07:40                     |
| - | 661  | ((micromachine micromachined<br>micromechanical (micromirror adj device))<br>) and substrate and (wire wiring)) and<br>(adhesive (sealing adj resin) encapsulant<br>encapsulated encapsualation)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 07:45                     |
| - | 655  | ((micromachine micromachined<br>micromechanical (micromirror adj device))<br>) and substrate and (wire wiring)) and<br>(adhesive (sealing adj resin) encapsulant<br>encapsulated encapsualation)) not<br>((micromachine micromachined<br>micromechanical micromirror<br>microelectronic) ) and ((block blocking)<br>near (adhesive material)))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 07:46                     |
| - | 486  | ((micromachine micromachined<br>micromechanical (micromirror adj device))<br>) and substrate and (wire wiring)) and<br>(adhesive (sealing adj resin) encapsulant<br>encapsulated encapsualation)) not<br>((micromachine micromachined<br>micromechanical micromirror<br>microelectronic) ) and ((block blocking)<br>near (adhesive material))) and wafer  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 07:46                     |
| - | 38   | ((micromachine micromachined<br>micromechanical (micromirror adj device))<br>) and substrate and (wire wiring)) and<br>(adhesive (sealing adj resin) encapsulant<br>encapsulated encapsualation)) not<br>((micromachine micromachined<br>micromechanical micromirror<br>microelectronic) ) and ((block blocking)<br>near (adhesive material))) and wafer) and<br>curable  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 07:54                     |
| - | 0    | 20020031847.URPN.   | USPAT                                       | 2002/03/25 07:49                     |

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|---|-----|---|---|------------------|
| - | 48  | (((((micromachine micromachined micromechanical (micromirror adj device)) ) and substrate and (wire wiring)) and (adhesive (sealing adj resin) encapsulant encapsulated encapsualation)) not ((micromachine micromachined micromechanical micromirror microelectronic) ) and ((block blocking) near (adhesive material)))) and curable                  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 07:54 |
| - | 10  | (((((micromachine micromachined micromechanical (micromirror adj device)) ) and substrate and (wire wiring)) and (adhesive (sealing adj resin) encapsulant encapsulated encapsualation)) not ((micromachine micromachined micromechanical micromirror microelectronic) ) and ((block blocking) near (adhesive material)))) and curable                  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 07:55 |
| - | 18  | not ((((((micromachine micromachined micromechanical (micromirror adj device)) ) and substrate and (wire wiring)) and (adhesive (sealing adj resin) encapsulant encapsulated encapsualation)) not ((micromachine micromachined micromechanical micromirror microelectronic) ) and ((block blocking) near (adhesive material)))) and wafer) and curable) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 08:05 |
| - | 0   | (micromachine micromachined micromechanical (micromirror adj device)) near3 (ccd (charge adj coupled adj device) (surface adj acoustical adj wave))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 08:11 |
| - | 0   | 6274927.pn. and curable   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 08:12 |
| - | 0   | 6143588.pn. and curable   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 10:20 |
| - | 0   | 6117705.pn. and curable   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 08:16 |
| - | 0   | 5866953.pn. and curable   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 08:16 |
| - | 3   | 5615052.pn.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 08:16 |
| - | 2   | 6185180.pn.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 08:16 |
| - | 5   | 6185180.pn. 5615052.pn.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 13:48 |
| - | 2   | 6117705.pn. and ("300" "310" "320" "325" "329")   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 14:07 |
| - | 0   | (hysol silicone) near3 stacky   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 13:55 |
| - | 377 | (hysol silicone) near3 tacky  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT |                  |

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| - | 0     | ((hysol silicone) near3 tacky) with (gettering getter)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 13:51 |
| - | 0     | ((hysol silicone) near3 tacky) and (gettering getter)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 13:51 |
| - | 33    | ((hysol silicone) near3 tacky) and micro   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 13:54 |
| - | 86    | ((hysol silicone) near3 tacky) and (semiconductor IC electronic chip die)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 13:54 |
| - | 1     | ((hysol silicone) near3 tacky) and (semiconductor IC electronic chip die)) and hysol   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 13:55 |
| - | 1     | adhesive near3 stacky  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 14:07 |
| - | 54209 | micromachine micromachined micromechanical micromirror microelectronic   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 14:25 |
| - | 14411 | (micromachine micromachined micromechanical micromirror microelectronic) and etching   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 14:26 |
| - | 1     | (micromachine micromachined micromechanical micromirror microelectronic) and (etching near3 (active adj surface))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 14:29 |
| - | 1     | (micromachine micromachined micromechanical micromirror microelectronic) and (etching near5 (active adj surface))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 14:30 |
| - | 19    | (micromachine micromachined micromechanical micromirror microelectronic) and (etching with (active adj surface))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 14:34 |
| - | 82    | (micromachine micromachined micromechanical micromirror microelectronic) and (etching with (resin adhesive encapsulant) with surface)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 14:36 |
| - | 81    | ((micromachine micromachined micromechanical micromirror microelectronic) and (etching with (resin adhesive encapsulant) with surface)) not ((micromachine micromachined micromechanical micromirror microelectronic) and (etching with (active adj surface))) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/03/25 14:37 |
| - | 4678  | (micromachine micromachined)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:00 |
| - | 346   | ((micromachine micromachined) ) and (cap lid) and substrate  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:18 |
| - | 37    | ((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:19 |
| - | 7     | ("5369057"   "5585675"   "5663596"   "5721162"   "5831162"   "5907187"   "6087203").PN.  | USPAT                                       | 2002/04/12 07:08 |
| - | 1     | 6225692.URPN.  | USPAT                                       | 2002/04/12 07:09 |

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| - | 4     | ("5610431"   "5719069"   "5915168"   "6074891").PN.  | USPAT                                       | 2002/04/12 07:10 |
| - | 6     | 5610431.URPN.  | USPAT                                       | 2002/04/12 07:11 |
| - | 0     | 6297072.URPN.  | USPAT                                       | 2002/04/12 07:12 |
| - | 9     | ("4769344"   "5296408"   "5317922"   "5335550"   "5430421"   "5602385"   "5610431"   "5929728"   "6124145").PN.  | USPAT                                       | 2002/04/12 07:12 |
| - | 28    | ("4548078"   "4680606"   "4744249"   "4744863"   "4764244"   "4853669"   "4855544"   "4861420"   "4874499"   "4904978"   "4996082"   "4996627"   "5013396"   "5075253"   "5101669"   "5165289"   "5207103"   "5233871"   "5233874"   "5264075"   "5295395"   "5296408"   "5318652"   "5323051"   "5324683"   "5326726"   "5335544"   "5343064").PN.                  | USPAT                                       | 2002/04/12 07:15 |
| - | 0     | 6214644.URPN.  | USPAT                                       | 2002/04/12 07:17 |
| - | 54707 | micromachine micromachined micromechanical micromirror microelectronic   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:18 |
| - | 252   | ((micromachine micromachined micromechanical micromirror microelectronic) and (cap lid) and substrate) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:34 |
| - | 234   | ((micromachine micromachined micromechanical micromirror microelectronic) and (cap lid) and substrate) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball)))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:20 |
| - | 0     | ((micromachine micromachined micromechanical micromirror microelectronic) and (cap lid) and substrate) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball)))) and ((electro magnetic) near2 shield) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:36 |
| - | 24    | ((micromachine micromachined micromechanical micromirror microelectronic) and (cap lid) and substrate) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball)))) and shield                            | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:36 |
| - | 240   | (micromachine micromachined micromechanical micromirror microelectronic) and ((insulating insulative dielectric insulation) near3 (cap lid))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:27 |

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| - | 240   | ((micromachine micromachined micromechanical micromirror microelectronic) and ((insulating insulative dielectric insulation) near3 (cap lid))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball)))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:27 |
| - | 1     | ((micromachine micromachined micromechanical micromirror microelectronic) and ((insulating insulative dielectric insulation) near3 (cap lid))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball))) and ((cap lid) near3 ((bond bonding metal conductive) near pad)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:30 |
| - | 2     | ((micromachine micromachined micromechanical micromirror microelectronic) and ((insulating insulative dielectric insulation) near3 (cap lid))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball))) and ((cap lid) with ((bond bonding metal conductive) near pad))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:29 |
| - | 16    | ((micromachine micromachined micromechanical micromirror microelectronic) and ((insulating insulative dielectric insulation) near3 (cap lid))) not (((micromachine micromachined) ) and (cap lid) and substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj ball))) and ((bond bonding metal conductive) near pad)                   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:36 |
| - | 30962 | semiconductor near2 (package packaging)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:33 |
| - | 3754  | (semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:34 |
| - | 1615  | ((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:42 |
| - | 930   | ((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:36 |
| - | 3     | ((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and ((electro magnetic) near2 shield)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:36 |
| - | 50    | ((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:37 |

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| - | 195    | ((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) with ((through adj hole) vias))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:53 |
| - | 181    | ((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) with ((through adj hole) vias)) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:43 |
| - | 376878 | ((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) with ((through adj hole) vias)) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield)) (stack stacked)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:43 |
| - | 44     | ((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) with ((through adj hole) vias)) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield)) and (stack stacked)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:55 |
| - | 1278   | ((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) and ((through adj hole) vias))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:54 |
| - | 1054   | ((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) and ((through adj hole) vias)) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield) not ((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) with ((through adj hole) vias)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:55 |



|   |      |  |   |                  |
|---|------|--|---|------------------|
| - | 1191 | ((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) and((through adj hole) vias))) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) with ((through adj hole) vias))) not (((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield)) and (stack stacked)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/12 07:55 |
| - | 0    | 6294406.URPN.  | USPAT                                       | 2002/04/12 08:09 |
| - | 16   | ("4703483"   "5109320"   "5323060"  <br>"5399898"   "5401672"   "5434453"  <br>"5446247"   "5495394"   "5541449"  <br>"5563773"   "5576519"   "5600541"  <br>"5760478"   "5770480"   "5790384"  <br>"6069025").PN.   | USPAT<br>USPAT                              | 2002/04/12 08:09 |
| - | 20   | 5600541.URPN.  | USPAT                                       | 2002/04/12 08:11 |
| - | 7    | 6025648.URPN.  | USPAT                                       | 2002/04/12 08:15 |
| - | 8    | ("5276289"   "5798567"   "5854507"  <br>"5869894"   "5936843"   "5969944"  <br>"5994166"   "6025648").PN.  | USPAT                                       | 2002/04/12 08:18 |
| - | 26   | ("3179913"   "3370203"   "3459998"  <br>"3904934"   "4288841"   "4502098"  <br>"4574331"   "4646128"   "4727410"  <br>"4823233"   "4833568"   "4862249"  <br>"4868712"   "4953005"   "5016138"  <br>"5019945"   "5674785"   "5854507"  <br>"5883426"   "5973392"   "6013948"  <br>"6020629"   "6025648"   "6072233"  <br>"6137164"   "6188127").PN.  | USPAT                                       | 2002/04/12 08:22 |
| - | 16   | ("4894706"   "5016138"   "5222014"  <br>"5247423"   "5600541"   "5633783"  <br>"5715144"   "5742477"   "5760478"  <br>"5786628"   "5798562"   "5801438"  <br>"5807986"   "5811879"   "5838060"  <br>"5838551").PN.   | USPAT                                       | 2002/04/12 08:26 |
| - | 95   | 5222014.URPN.  | USPAT                                       | 2002/04/12 08:30 |
| - | 24   | 5790384.URPN.  | USPAT                                       | 2002/04/12 08:30 |
| - | 22   | 5783870.URPN.  | USPAT                                       | 2002/04/12 09:10 |
| - | 36   | ("3436603"   "4807021"   "4867235"  <br>"4933810"   "4953060"   "4991000"  <br>"5060844"   "5099309"   "5128831"  <br>"5130894"   "5172303"   "5222014"  <br>"5241133"   "5241450"   "5241456"  <br>"5247423"   "5299094"   "5307240"  <br>"5313366"   "5376825"   "5391917"  <br>"5394010"   "5394300"   "5397917"  <br>"5412538"   "5421081"   "5422435"  <br>"5454160"   "5579207"   "5615089"  <br>"5633783"   "5642265"   "5739581"  <br>"5783870"   "5798564"   "5920117").PN.   | USPAT<br>USPAT<br>USPAT<br>USPAT            | 2002/04/12 09:13 |

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|---|----|---|---|------------------|
| - | 40 | (US-6025767-\$ or US-6163061-\$ or<br>US-6323550-\$ or US-6225692-\$ or<br>US-6214644-\$ or US-5694740-\$ or<br>US-6140144-\$ or US-5532513-\$ or<br>US-4965660-\$ or US-4729010-\$ or<br>US-6342406-\$ or US-6274927-\$ or<br>US-6143588-\$ or US-5962810-\$ or<br>US-5866953-\$ or US-6117705-\$ or<br>US-5644169-\$ or US-6185180-\$ or<br>US-5615052-\$ or US-5610431-\$ or<br>US-5730922-\$ or US-5549870-\$ or<br>US-6297072-\$ or US-5430421-\$ or<br>US-6274929-\$ or US-6369448-\$).did. or<br>(US-6340894-\$ or US-6313522-\$ or<br>US-5790384-\$ or US-5600541-\$ or<br>US-6025648-\$ or US-5936843-\$ or<br>US-6188127-\$ or US-5247423-\$ or<br>US-5222014-\$ or US-6101100-\$ or<br>US-5783870-\$ or US-5579207-\$).did. or<br>(US-20010026010-\$ or<br>US-20010008794-\$).did.   | USPAT;<br>US-PGPUB                          | 2002/04/15 09:08 |
| - | 3  | ((US-6025767-\$ or US-6163061-\$ or<br>US-6323550-\$ or US-6225692-\$ or<br>US-6214644-\$ or US-5694740-\$ or<br>US-6140144-\$ or US-5532513-\$ or<br>US-4965660-\$ or US-4729010-\$ or<br>US-6342406-\$ or US-6274927-\$ or<br>US-6143588-\$ or US-5962810-\$ or<br>US-5866953-\$ or US-6117705-\$ or<br>US-5644169-\$ or US-6185180-\$ or<br>US-5615052-\$ or US-5610431-\$ or<br>US-5730922-\$ or US-5549870-\$ or<br>US-6297072-\$ or US-5430421-\$ or<br>US-6274929-\$ or US-6369448-\$).did. or<br>(US-6340894-\$ or US-6313522-\$ or<br>US-5790384-\$ or US-5600541-\$ or<br>US-6025648-\$ or US-5936843-\$ or<br>US-6188127-\$ or US-5247423-\$ or<br>US-5222014-\$ or US-6101100-\$ or<br>US-5783870-\$ or US-5579207-\$).did. or<br>(US-20010026010-\$ or<br>US-20010008794-\$).did.) and (emi (electro<br>nearl magnetic neaerl shield)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/15 09:11 |
| - | 1  | ((US-6025767-\$ or US-6163061-\$ or<br>US-6323550-\$ or US-6225692-\$ or<br>US-6214644-\$ or US-5694740-\$ or<br>US-6140144-\$ or US-5532513-\$ or<br>US-4965660-\$ or US-4729010-\$ or<br>US-6342406-\$ or US-6274927-\$ or<br>US-6143588-\$ or US-5962810-\$ or<br>US-5866953-\$ or US-6117705-\$ or<br>US-5644169-\$ or US-6185180-\$ or<br>US-5615052-\$ or US-5610431-\$ or<br>US-5730922-\$ or US-5549870-\$ or<br>US-6297072-\$ or US-5430421-\$ or<br>US-6274929-\$ or US-6369448-\$).did. or<br>(US-6340894-\$ or US-6313522-\$ or<br>US-5790384-\$ or US-5600541-\$ or<br>US-6025648-\$ or US-5936843-\$ or<br>US-6188127-\$ or US-5247423-\$ or<br>US-5222014-\$ or US-6101100-\$ or<br>US-5783870-\$ or US-5579207-\$).did. or<br>(US-20010026010-\$ or<br>US-20010008794-\$).did.) and (emi<br>(electromagnetic nearl shield))         | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/15 09:12 |

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|---|------|---|---|------------------|
| - | 1    | ((US-6025767-\$ or US-6163061-\$ or<br>US-6323550-\$ or US-6225692-\$ or<br>US-6214644-\$ or US-5694740-\$ or<br>US-6140144-\$ or US-5532513-\$ or<br>US-4965660-\$ or US-4729010-\$ or<br>US-6342406-\$ or US-6274927-\$ or<br>US-6143588-\$ or US-5962810-\$ or<br>US-5866953-\$ or US-6117705-\$ or<br>US-5644169-\$ or US-6185180-\$ or<br>US-5615052-\$ or US-5610431-\$ or<br>US-5730922-\$ or US-5549870-\$ or<br>US-6297072-\$ or US-5430421-\$ or<br>US-6274929-\$ or US-6369448-\$).did. or<br>(US-6340894-\$ or US-6313522-\$ or<br>US-5790384-\$ or US-5600541-\$ or<br>US-6025648-\$ or US-5936843-\$ or<br>US-6188127-\$ or US-5247423-\$ or<br>US-5222014-\$ or US-6101100-\$ or<br>US-5783870-\$ or US-5579207-\$).did. or<br>(US-20010026010-\$ or<br>US-20010008794-\$).did.) and (emi<br>(electromagnetic near1 interference)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/15 09:16 |
| - | 2191 | (micromachine micromachined<br>micromechanical micromirror<br>microelectronic) and (cap lid) and<br>substrate   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/15 09:16 |
| - | 108  | ((micromachine micromachined<br>micromechanical micromirror<br>microelectronic) and (cap lid) and<br>substrate) and (emi (electromagnetic near1<br>(shield interference)) (electro adj<br>magnetic adj interference))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/15 09:18 |
| - | 64   | ((micromachine micromachined<br>micromechanical micromirror<br>microelectronic) and (cap lid) and<br>substrate) and ((electromagnetic near1<br>(shield interference)) (electro adj<br>magnetic adj interference))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/15 09:18 |
| - | 30   | ((micromachine micromachined<br>micromechanical micromirror<br>microelectronic) and (cap lid) and<br>substrate) and (emi (electromagnetic near1<br>(shield interference)) (electro adj<br>magnetic adj interference))) and<br>(semiconductor near1 (device package<br>packaging))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/15 09:41 |
| - | 10   | 5639989.pn. 5578525.pn. 5981314.pn.<br>6150716.pn. 6308938.pn   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/04/15 09:42 |

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|---|----|---|--------------------|------------------|
| - | 44 | (US-5694740-\$ or US-5644169-\$ or<br>US-5615052-\$ or US-5600541-\$ or<br>US-5610431-\$ or US-5579207-\$ or<br>US-5532513-\$ or US-5549870-\$ or<br>US-5222014-\$ or US-5247423-\$ or<br>US-5430421-\$ or US-4965660-\$ or<br>US-4729010-\$ or US-6262362-\$ or<br>US-6064126-\$ or US-5880403-\$ or<br>US-5821762-\$ or US-6369448-\$ or<br>US-6342406-\$ or US-6313522-\$ or<br>US-6323550-\$ or US-6340894-\$ or<br>US-6274929-\$ or US-6297072-\$ or<br>US-6225692-\$ or US-6274927-\$).did. or<br>(US-6185180-\$ or US-6188127-\$ or<br>US-6143588-\$ or US-6214644-\$ or<br>US-6163061-\$ or US-6025767-\$ or<br>US-6140144-\$ or US-6117705-\$ or<br>US-6101100-\$ or US-5962810-\$ or<br>US-6025648-\$ or US-5936843-\$ or<br>US-5790384-\$ or US-5866953-\$ or<br>US-5783870-\$ or US-5730922-\$).did. or<br>(US-20010008794-\$ or<br>US-20010026010-\$).did. | USPAT;<br>US-PGPUB | 2002/07/17 15:11 |
| - | 17 | ("4801998"   "5222014"   "5231036"  <br>"5578525"   "5579207"   "5786589"  <br>"5821532"   "5867368"   "5907151"  <br>"5962810"   "5973337"   "6046070"  <br>"6122009"   "6143981"   "6144507"  <br>"6247229"   "6281568").PN.  | USPAT              | 2002/07/17 15:30 |
| - | 16 | ("5012323"   "5121293"   "5128831"  <br>"5189505"   "5289337"   "5291061"  <br>"5323060"   "5385869"   "5422435"  <br>"5434745"   "5474957"   "5495398"  <br>"5513076"   "5607099"   "5963430"  <br>"6020629").PN.  | USPAT              | 2002/07/17 15:33 |
| - | 2  | 6313522.URPN.   | USPAT              | 2002/07/17 15:34 |
| - | 9  | ("4769344"   "5296408"   "5317922"  <br>"5335550"   "5430421"   "5602385"  <br>"5610431"   "5929728"   "6124145").PN.   | USPAT              | 2002/07/17 15:35 |
| - | 0  | 6297072.URPN.   | USPAT              | 2002/07/17 15:36 |
| - | 26 | ("3179913"   "3370203"   "3459998"  <br>"3904934"   "4288841"   "4502098"  <br>"4574331"   "4646128"   "4727410"  <br>"4823233"   "4833568"   "4862249"  <br>"4868712"   "4953005"   "5016138"  <br>"5019945"   "5674785"   "5854507"  <br>"5883426"   "5973392"   "6013948"  <br>"6020629"   "6025648"   "6072233"  <br>"6137164"   "6188127").PN.   | USPAT<br>USPAT     | 2002/07/17 15:37 |
| - | 4  | ("5610431"   "5719069"   "5915168"  <br>"6074891").PN.  | USPAT              | 2002/07/17 15:39 |
| - | 0  | 6214644.URPN.   | USPAT              | 2002/07/17 15:40 |
| - | 4  | 6025767.URPN.   | USPAT              | 2002/07/17 15:41 |
| - | 20 | ("0557132"   "3244947"   "3259814"  <br>"3274458"   "3316465"   "3489965"  <br>"3916080"   "3959577"   "3993123"  <br>"4168480"   "4257905"   "4449580"  <br>"4511873"   "4563697"   "4565901"  <br>"4897508"   "5046161"   "5325265"  <br>"5475280"   "5627396").PN.   | USPAT              | 2002/07/17 15:42 |
| - | 8  | 5610431.URPN.   | USPAT              | 2002/07/17 15:44 |
| - | 0  | 6373130.URPN.   | USPAT              | 2002/07/17 15:46 |
| - | 2  | ("5578869"   "5610431").PN.   | USPAT              | 2002/07/17 15:46 |

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|---|------|---|---|------------------|
| - | 28   | ("4548078"   "4680606"   "4744249"  <br>"4744863"   "4764244"   "4853669"  <br>"4855544"   "4861420"   "4874499"  <br>"4904978"   "4996082"   "4996627"  <br>"5013396"   "5075253"   "5101669"  <br>"5165289"   "5207103"   "5233871"  <br>"5233874"   "5264075"   "5295395"  <br>"5296408"   "5318652"   "5323051"  <br>"5324683"   "5326726"   "5335544"  <br>"5343064").PN.  | USPAT                                       | 2002/07/17 15:47 |
| - | 45   | (US-6140144-\$ or US-5532513-\$ or<br>US-4729010-\$ or US-4965660-\$ or<br>US-6185180-\$ or US-5615052-\$ or<br>US-6274927-\$ or US-6342406-\$ or<br>US-6143588-\$ or US-5962810-\$ or<br>US-5866953-\$ or US-5730922-\$ or<br>US-5549870-\$ or US-6117705-\$ or<br>US-5644169-\$ or US-5610431-\$ or<br>US-6297072-\$ or US-5430421-\$ or<br>US-6025767-\$ or US-6163061-\$ or<br>US-6323550-\$ or US-6225692-\$ or<br>US-6214644-\$ or US-5694740-\$ or<br>US-5790384-\$ or US-5600541-\$).did. or<br>(US-6025648-\$ or US-6369448-\$ or<br>US-6274929-\$ or US-5936843-\$ or<br>US-6188127-\$ or US-5247423-\$ or<br>US-5222014-\$ or US-6101100-\$ or<br>US-5783870-\$ or US-5579207-\$ or<br>US-6340894-\$ or US-6313522-\$ or<br>US-6262362-\$ or US-6064126-\$ or<br>US-5880403-\$ or US-5821762-\$ or<br>US-6373130-\$).did. or (US-20010026010-\$ or<br>US-20010008794-\$).did.                            | USPAT;<br>US-PGPUB                          | 2002/07/22 09:11 |
| - | 1348 | 257/659 257/660   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/07/22 09:37 |
| - | 3    | (257/659 257/660) and ((US-6140144-\$ or<br>US-5532513-\$ or US-4729010-\$ or<br>US-4965660-\$ or US-6185180-\$ or<br>US-5615052-\$ or US-6274927-\$ or<br>US-6342406-\$ or US-6143588-\$ or<br>US-5962810-\$ or US-5866953-\$ or<br>US-5730922-\$ or US-5549870-\$ or<br>US-6117705-\$ or US-5644169-\$ or<br>US-5610431-\$ or US-6297072-\$ or<br>US-5430421-\$ or US-6025767-\$ or<br>US-6163061-\$ or US-6323550-\$ or<br>US-6225692-\$ or US-6214644-\$ or<br>US-5694740-\$ or US-5790384-\$ or<br>US-5600541-\$).did. or (US-6025648-\$ or<br>US-6369448-\$ or US-6274929-\$ or<br>US-5936843-\$ or US-6188127-\$ or<br>US-5247423-\$ or US-5222014-\$ or<br>US-6101100-\$ or US-5783870-\$ or<br>US-5579207-\$ or US-6340894-\$ or<br>US-6313522-\$ or US-6262362-\$ or<br>US-6064126-\$ or US-5880403-\$ or<br>US-5821762-\$ or US-6373130-\$).did. or<br>(US-20010026010-\$ or<br>US-20010008794-\$).did.) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/07/22 09:18 |
| - | 10   | 5880403.URPN.   | USPAT                                       | 2002/07/22 09:12 |
| - | 7    | ("4089575"   "4506108"   "4967315"  <br>"5239126"   "5250845"   "5406117"  <br>"5635754").PN.   | USPAT                                       | 2002/07/22 09:16 |
| - | 35   | (257/659 257/660) and (flipchip (flip adj<br>chip)) and (cap lid)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/07/22 09:18 |
| - | 18   | 5656857.URPN.   | USPAT                                       | 2002/07/22 09:28 |

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|---|-----|--|---|------------------|
| - | 9   | "4823523"  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/07/22 09:33 |
| - | 18  | "4868716"  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/07/22 09:33 |
| - | 19  | "4266239"  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/07/22 09:33 |
| - | 38  | "4823523" "4868716" "4266239"  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/07/22 09:36 |
| - | 3   | ((US-6140144-\$ or US-5532513-\$ or<br>US-4729010-\$ or US-4965660-\$ or<br>US-6185180-\$ or US-5615052-\$ or<br>US-6274927-\$ or US-6342406-\$ or<br>US-6143588-\$ or US-5962810-\$ or<br>US-5866953-\$ or US-5730922-\$ or<br>US-5549870-\$ or US-6117705-\$ or<br>US-5644169-\$ or US-5610431-\$ or<br>US-6297072-\$ or US-5430421-\$ or<br>US-6025767-\$ or US-6163061-\$ or<br>US-6323550-\$ or US-6225692-\$ or<br>US-6214644-\$ or US-5694740-\$ or<br>US-5790384-\$ or US-5600541-\$).did. or<br>(US-6025648-\$ or US-6369448-\$ or<br>US-6274929-\$ or US-5936843-\$ or<br>US-6188127-\$ or US-5247423-\$ or<br>US-5222014-\$ or US-6101100-\$ or<br>US-5783870-\$ or US-5579207-\$ or<br>US-6340894-\$ or US-6313522-\$ or<br>US-6262362-\$ or US-6064126-\$ or<br>US-5880403-\$ or US-5821762-\$ or<br>US-6373130-\$).did. or (US-20010026010-\$ or<br>US-20010008794-\$).did.) and emi | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/07/22 09:36 |
| - | 373 | 257/660  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/07/22 09:37 |
| - | 0   | 257/660 and micromachine   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/07/22 09:37 |
| - | 190 | 257/660 and (cap lid via (through adj<br>hole))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/07/22 09:38 |
| - | 49  | (257/660 and (cap lid via (through adj<br>hole))) and (bump ball)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2002/07/22 09:38 |

|   |    |  |                    |                  |
|---|----|--|--------------------|------------------|
| - | 45 | (US-6025767-\$ or US-6163061-\$ or<br>US-6225692-\$ or US-6323550-\$ or<br>US-6214644-\$ or US-5694740-\$ or<br>US-5532513-\$ or US-4729010-\$ or<br>US-4965660-\$ or US-6342406-\$ or<br>US-6274927-\$ or US-6143588-\$ or<br>US-5962810-\$ or US-5866953-\$ or<br>US-6117705-\$ or US-5644169-\$ or<br>US-6140144-\$ or US-6185180-\$ or<br>US-5615052-\$ or US-5730922-\$ or<br>US-5549870-\$ or US-5610431-\$ or<br>US-6297072-\$ or US-5430421-\$ or<br>US-5790384-\$ or US-5600541-\$).did. or<br>(US-6274929-\$ or US-6025648-\$ or<br>US-6369448-\$ or US-5936843-\$ or<br>US-6188127-\$ or US-5247423-\$ or<br>US-5222014-\$ or US-6101100-\$ or<br>US-5783870-\$ or US-5579207-\$ or<br>US-6340894-\$ or US-6313522-\$ or<br>US-6262362-\$ or US-6064126-\$ or<br>US-5880403-\$ or US-5821762-\$ or<br>US-6373130-\$).did. or (US-20010026010-\$ or<br>US-20010008794-\$).did. | USPAT;<br>US-PGPUB | 2003/09/05 08:58 |
|---|----|--|--------------------|------------------|